

February, 2009

### FPDB60PH60B

### **Smart Power Module for Front-End Rectifier**

### **General Description**

FPDB60PH60B is an advanced smart power module of PFC(Power Factor Correction) that Fairchild has newly developed and designed mainly targeting mid-power application especially for an air conditioners. It combines optimized circuit protection and drive IC matched to high frequency switching IGBTs. System reliability is futher enhanced by the integrated under-voltage lock-out and over-current protection function.

### **Features**

- Low thermal resistance due to AIN-DBC substrate
- 600V-60A 2-phase IGBT PWM semi-converter including a drive IC for gate driving and protection
- Typical switching frequency of 20kHz
- Isolation rating of 2500Vrms/min.

### **Applications**

• AC 180V ~ 264V single-phase front-end rectifier

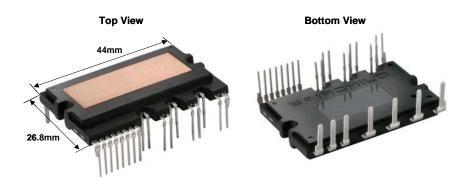


Fig. 1.

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### **Integrated Power Functions**

• PFC converter for single-phase AC/DC power conversion (Please refer to Fig. 3)

### Integrated Drive, Protection and System Control Functions

- For IGBTs: Gate drive circuit, Overcurrent circuit protection (OC), Control supply circuit under-voltage (UV) protection
- Fault signaling: Corresponding to a UV fault
- Input interface: 5V CMOS/LSTTL compatible, Schmitt trigger input

### **Pin Configuration**

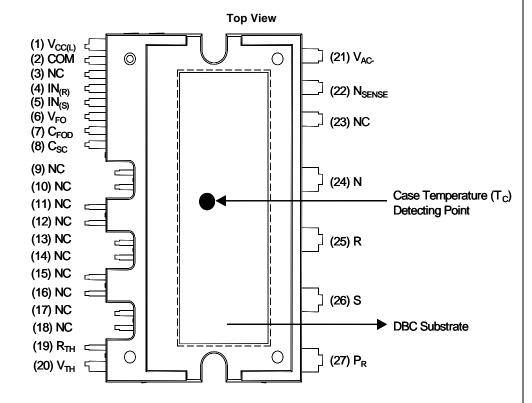
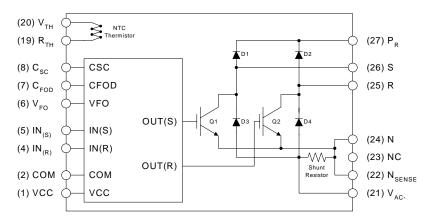


Fig. 2.

### **Pin Descriptions**

Pin Number	Pin Name	Pin Description
1	V <sub>CC</sub>	Common Bias Voltage for IC and IGBTs Driving
2	COM	Common Supply Ground
4	IN <sub>(R)</sub>	Signal Input for Low-side R-phase IGBT
5	IN <sub>(S)</sub>	Signal Input for Low-side S-phase IGBT
6	V <sub>FO</sub>	Fault Output
7	C <sub>FOD</sub>	Capacitor for Fault Output Duration Time Selection
8	C <sub>SC</sub>	Capacitor (Low-pass Filter) for Over Current Detection
19	R <sub>(TH)</sub>	NTC Thermistor terminal
20	V <sub>(TH)</sub>	NTC Thermistor terminal
21	V <sub>AC-</sub>	Current Sensing Terminal
22	N <sub>SENSE</sub>	Current Sensing Reference Terminal
24	N	Negative Rail of DC-Link
25	R	Output for R Phase
26	S	Output for S Phase
27	$P_{R}$	Positive Rail of DC-Link
3, 9~18, 23	NC	No Connection

## **Internal Equivalent Circuit and Input/Output Pins**



Note:
1) Converter is composed of two IGBTs including four diodes and one IC which has gate driving and protection functions.

Fig. 3.

# **Absolute Maximum Ratings** (T<sub>J</sub> = 25°C, Unless Otherwise Specified)

### **Converter Part**

Item	Symbol	Condition	Rating	Unit
Supply Voltage	V <sub>i</sub>	Applied between R-S	264	$V_{RMS}$
Supply Voltage (Surge)	V <sub>i(Surge)</sub>	Applied between R-S	500	V
Output Voltage	$V_{PN}$	Applied between P- N	450	V
Output Voltage (Surge)	V <sub>PN(Surge)</sub>	Applied between P- N	500	V
Collector-emitter Voltage	V <sub>CES</sub>		600	V
Each IGBT collector current	± I <sub>C</sub>	T <sub>C</sub> = 25°C	60	Α
Each IGBT collector current (Peak)	± I <sub>CP</sub>	T <sub>C</sub> = 25°C, Under 1ms pulse width	90	Α
Collector Dissipation	P <sub>C</sub>	T <sub>C</sub> = 25°C per One IGBT	178	W
Repetitive Peak Reverse Voltage	$V_{RRM}$		600	V
Peak Forward Surge Current	I <sub>FSM</sub>	Single half sine-wave	350	Α
Power Rating of Shunt Resistor	P <sub>RSH</sub>	T <sub>C</sub> < 125°C	2	W
Operating Junction Temperature	T <sub>J</sub>	(Note 1)	-40 ~ 150	°C

### **Control Part**

Item	Symbol	Condition	Rating	Unit
Control Supply Voltage	V <sub>CC</sub>	Applied between V <sub>CC</sub> - COM	20	V
Input Signal Voltage	V <sub>IN</sub>	Applied between IN - COM	-0.3~17	V
Fault Output Supply Voltage	$V_{FO}$	Applied between V <sub>FO</sub> - COM	-0.3~V <sub>CC</sub> +0.3	V
Fault Output Current	I <sub>FO</sub>	Sink Current at V <sub>FO</sub> Pin	5	mA
Current Sensing Input Voltage	V <sub>SC</sub>	Applied between C <sub>SC</sub> - COM	-0.3~V <sub>CC</sub> +0.3	V

### **Total System**

Item	Symbol	Condition	Rating	Unit
Module Case Operation Temperature	T <sub>C</sub>		-20 ~ 100	°C
Storage Temperature	T <sub>STG</sub>		-40 ~ 150	°C
Isolation Voltage	V <sub>ISO</sub>	60Hz, Sinusoidal, AC 1 minute, Connection Pins to DBC	2500	V <sub>rms</sub>

### **Thermal Resistance**

Item	Symbol	Condition	Min.	Тур.	Max.	Unit
Junction to Case Thermal	$R_{\theta(j-c)Q}$	IGBT	-	-	0.7	°C/W
Resistance	$R_{\theta(j-c)HD}$	High-side diode	-	-	1.5	°C/W
(Referenced to PKG center)	$R_{\theta(j-c)LD}$	Low-side diode	-	-	0.85	°C/W

### Note:

Note: 1. The maximum junction temperature rating of the power chips integrated within the SPM is  $150^{\circ}\text{C}(@T_{C} \le 100^{\circ}\text{C})$ . However, to insure safe operation of the SPM, the average junction temperature should be limited to  $T_{J(ave)} \le 125^{\circ}\text{C}$  ( $@T_{C} \le 100^{\circ}\text{C}$ ).

<sup>2.</sup> For the measurement point of case temperature( $T_{\mbox{\scriptsize C}}$ ), please refer to Fig. 2.

# $\textbf{Electrical Characteristics} \ \, (T_J = 25^{\circ}\text{C}, \, \text{Unless Otherwise Specified})$

### **Converter Part**

Item	Symbol	Condition	Min.	Тур.	Max.	Unit
IGBT saturation voltage	V <sub>CE(sat)</sub>	$V_{CC} = 15V, V_{IN} = 5V; I_{C} = 50A$	-	2.0	2.5	V
High-side diode voltage	V <sub>FH</sub>	I <sub>F</sub> = 50A	-	2.4	2.9	V
Low-side diode voltage	$V_{FL}$	I <sub>F</sub> = 50A	-	1.2	1.6	V
Switching Times	t <sub>ON</sub>	V <sub>PN</sub> = 400V, V <sub>CC</sub> = 15V, I <sub>C</sub> =60A	-	560	-	ns
	t <sub>C(ON)</sub>	V <sub>IN</sub> = 0V ↔ 5V, Inductive Load	-	270	-	ns
	t <sub>OFF</sub>	(Note 3)	-	520	-	ns
	t <sub>C(OFF)</sub>	(1.010.0)	-	110	-	ns
	t <sub>rr</sub>		-	44	-	ns
	I <sub>rr</sub>		-	6.5	-	Α
Current sensing resistor	R <sub>SENSE</sub>		1.8	2.0	2.2	mΩ
Collector - emitter Leakage Current	I <sub>CES</sub>	V <sub>CE</sub> = V <sub>CES</sub>	-	-	250	μА

### **Control Part**

Item	Symbol	С	ondition	Min.	Тур.	Max.	Unit
Quiescent V <sub>CC</sub> Supply Current	I <sub>QCCL</sub>	V <sub>CC</sub> = 15V, IN = 0V	V <sub>CC</sub> - COM	-	-	26	mA
Fault Output Voltage	$V_{FOH}$	V <sub>SC</sub> = 0V, V <sub>FO</sub> Circui	t: 4.7kΩ to 5V Pull-up	4.5	-	-	V
	$V_{FOL}$	V <sub>SC</sub> = 1V, V <sub>FO</sub> Circui	t: 4.7kΩ to 5V Pull-up	-	-	0.8	V
Over Current Trip Level	V <sub>SC(ref)</sub>	V <sub>CC</sub> = 15V		0.45	0.5	0.55	V
Supply Circuit Under-	UV <sub>CCD</sub>	Detection Level		10.7	11.9	13.0	V
Voltage Protection	UV <sub>CCR</sub>	Reset Level		11.2	12.4	13.2	V
Fault-out Pulse Width	t <sub>FOD</sub>	C <sub>FOD</sub> = 33nF (Note 4)		1.4	1.8	2.0	ms
ON Threshold Voltage	V <sub>IN(ON)</sub>	Applied between IN - COM		3.0	-	-	V
OFF Threshold Voltage	V <sub>IN(OFF)</sub>			-	-	0.8	V
Resistance of Thermistor	R <sub>TH</sub>	@ T <sub>C</sub> = 25°C (Note F	ig. 9)	-	50	-	kΩ
		@ T <sub>C</sub> = 80°C (Note F	ig. 9)	-	5.76	-	kΩ

### **Recommended Operating conditions**

Item	Symbol	Condition	Min.	Тур.	Max.	Unit
Input Supply Voltage	V <sub>I</sub>	Applied between R - S	180	-	264	$V_{rms}$
Output Voltage	$V_{PN}$	Applied between P - N	-	280	400	V
Control Supply Voltage	V <sub>CC</sub>	Applied between V <sub>CC</sub> - COM	13.5	15	16.5	V
Control Supply Variation	dV <sub>CC</sub> /dt	Applied between IN - COM	-1	-	1	V/μs
PWM Input Signal	f <sub>PWM</sub>	$T_C \le 100$ °C, $T_J \le 125$ °C, Per IGBT	-	20	-	kHz

Note
3. toN and toFF include the propagation delay time of the internal drive IC. tc(ON) and tc(OFF) are the switching time of IGBT itself under the given gate driving condition internally. For the detailed information, please see Fig. 4

Note
4. The fault-out pulse width  $t_{FOD}$  depends on the capacitance value of  $C_{FOD}$  according to the following approximate equation :  $C_{FOD} = 18.3 \times 10^{-6} \times t_{FOD}[F]$ 

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### **Electrical Characteristics**

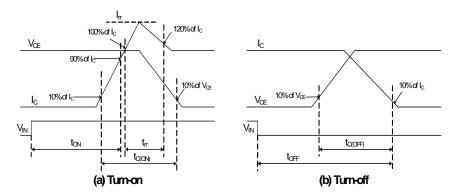


Fig. 4. Switching Time Definition

## **Mechanical Characteristics and Ratings**

ltom		Condition		l luite		
Item	•	Min.	Тур.	Max.	Units	
Mounting Torque	Mounting Screw: - M3	Recommended 0.62N•m	0.51	0.62	0.72	N•m
Device Flatness	Note Fig. 5	•	0	-	+120	μm
Weight			-	15.00	-	g

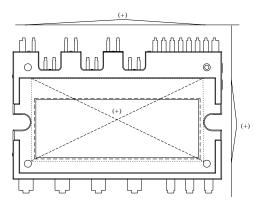
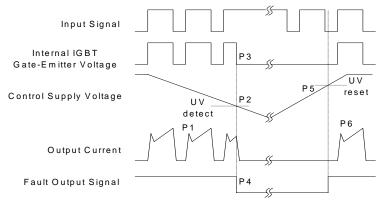


Fig. 5. Flatness Measurement Position

### **Time Charts of SPMs Protective Function**

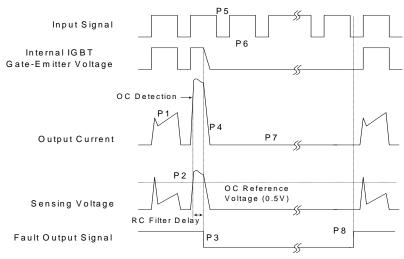


P1: Normal operation - IGBT ON and conducting current

P2 : Under voltage detection P3 : IGBT gate interrupt P4 : Fault signal generation P5 : Under voltage reset

P6: Normal operation - IGBT ON and conducting current

Fig. 6. Under-Voltage Protection



P1: Normal operation - IGBT ON and conducting current

P2 : Over current detection

P3: IGBT gate interrupt / Fault signal generation

P4: IGBT is slowly turned off

P5 : IGBT OFF signal

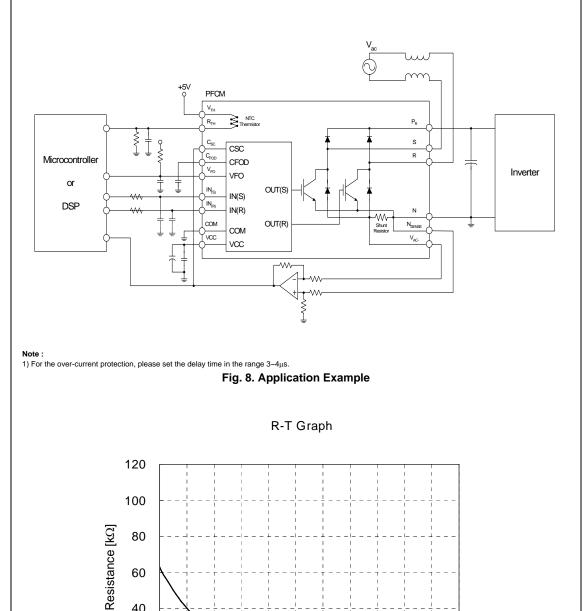
P6: IGBT ON signal - but IGBT cannot be turned on during the fault Output activation

P7: IGBT OFF state

P8 : Fault Output reset and normal operation start

Fig. 7. Over Current Protection

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Temperature [°C] Fig. 9. R-T Curve of the Built-in Thermistor

40 50 60 70 80 90 100 110 120 130

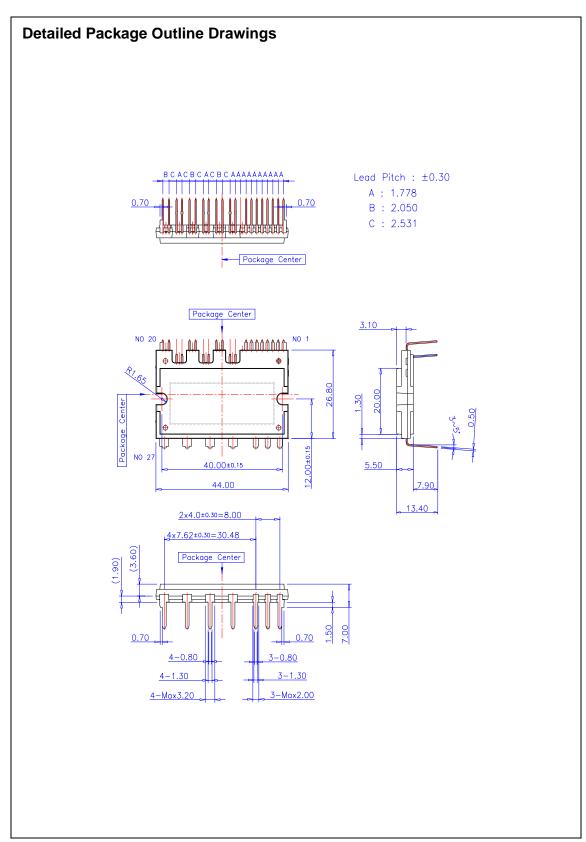
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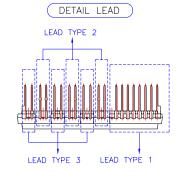
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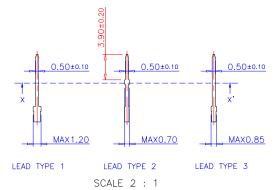
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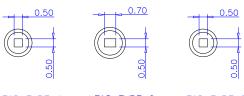


# **Detailed Package Outline Drawings** 30.60 26.50 11.90±0.30 27.90±0.30 4.10±0.30 Lead Forming Dimension Package Center Package Center (2.76)(2.76)19.694±0.30 20.447±0.30 19.24±0.30 19.24±0.30 PKG Center to Lead Distance

# **Detailed Package Outline Drawings**







LEAD TYPE 1 LEAD TYPE 2 LEAD TYPE 3

SCALE 5 : 1

LEAD SECTION X-X'

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